## **Zhong Zhao**

## List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/8657613/publications.pdf

Version: 2024-02-01

|               |                     | 1684188           | 1720034           |
|---------------|---------------------|-------------------|-------------------|
| 8             | 83                  | 5                 | 7                 |
| papers        | citations           | h-index           | g-index           |
|               |                     |                   |                   |
| 8<br>all docs | 8<br>docs citations | 8<br>times ranked | 60 citing authors |
|               |                     |                   |                   |

| # | Article   | IF  | CITATIONS |
|---|---|-----|-----------|
| 1 | Enhancing the adhesion strength of micro electroforming layer by ultrasonic agitation method and the application. Ultrasonics Sonochemistry, 2016, 33, 10-17.   | 8.2 | 28        |
| 2 | Effects of ultrasonic agitation on adhesion strength of micro electroforming Ni layer on Cu substrate. Ultrasonics Sonochemistry, 2016, 29, 1-10.   | 8.2 | 24        |
| 3 | Influence of electrodeposited crystallite size on interfacial adhesion strength of electroformed layers. Micro and Nano Letters, 2014, 9, 73-76.  | 1.3 | 11        |
| 4 | Quantitative relationship between crystallite size and adhesion strength of the electroforming layer during microelectroforming process. Micro and Nano Letters, 2015, 10, 64-66.                             | 1.3 | 6         |
| 5 | Effect of dislocation density on adhesion strength of electroforming Ni layer on Cu substrate.<br>Journal of Adhesion Science and Technology, 2019, 33, 301-313.  | 2.6 | 6         |
| 6 | Reducing the internal compressive stress of the microelectroformed layer by adjusting the current densities. Micro and Nano Letters, 2019, 14, 1178-1181.   | 1.3 | 4         |
| 7 | A new ultrasonic electrochemical potential activation method to enhance the adhesion strength between electroforming layer and Cu substrate. Journal of Adhesion Science and Technology, 2021, 35, 2023-2034. | 2.6 | 3         |
| 8 | To reduce the passivation layer of Cu substrate by the ultrasonic assisted electrochemical potential activation method. Micro and Nano Letters, 0, , .  | 1.3 | 1         |